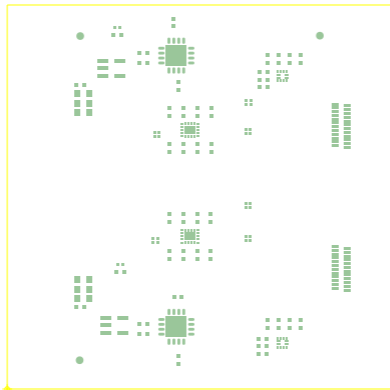
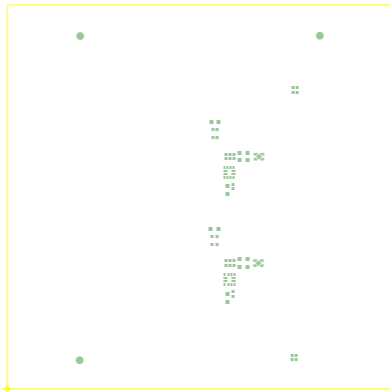
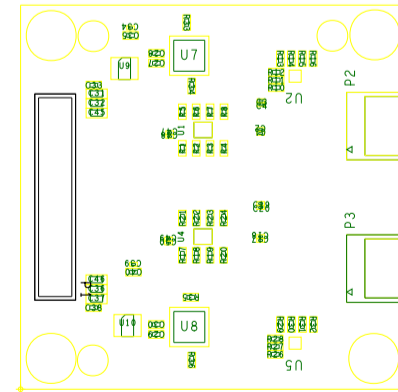
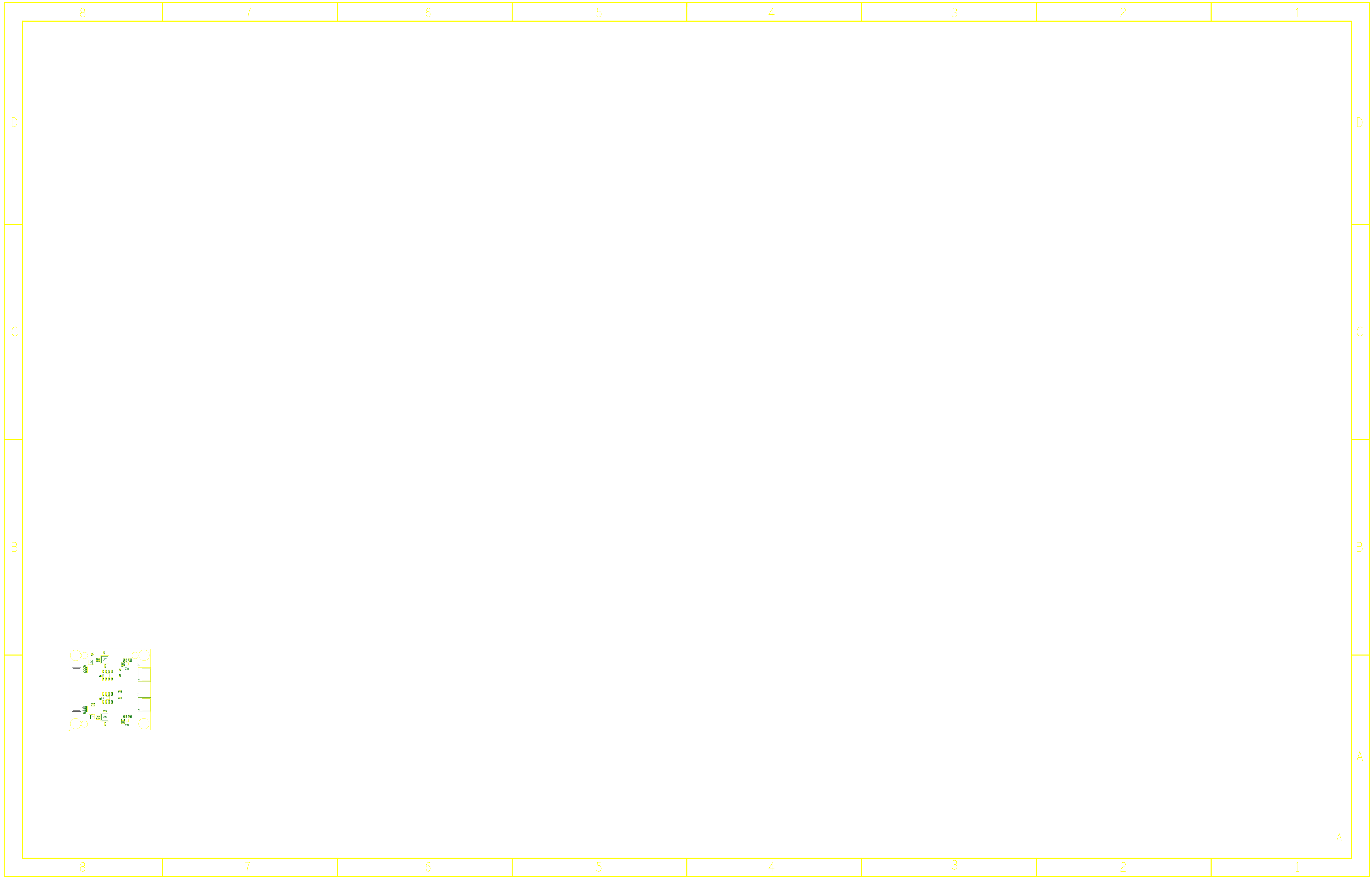


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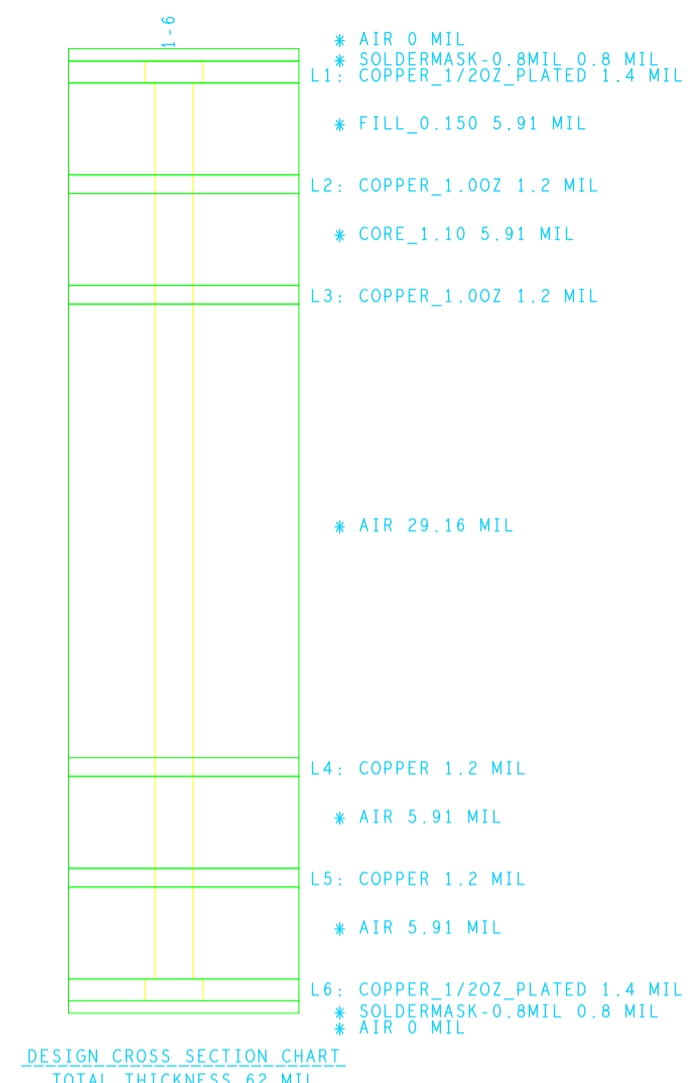


TABLE 1:

LAYER NO.	LAYER NAME	DIFFERENTIAL PAIR IMPEDANCE (OHMS)	DIFF TRACE WIDTH	DIFF TRACE SPACING	SINGLE ENDED IMPEDANCE (OHMS)	SINGLE ENDED TRACE WIDTH	REFERENCE LAYER
LAYER 1	TOP	90 +/- 10%	0.0055"	0.0045"			LAYER 2
LAYER 2	L2_GND						
LAYER 3	L3_PWR						
LAYER 4	L4_PWR						
LAYER 5	L5_GND						
LAYER 6	BOTTOM	90 +/- 10%	0.0055"	0.0045"			LAYER 5

SPECIAL FAB NOTES:

- 1: FAB SHOP MUST FOLLOW THE SOLDER MASK REVIEW LAYERS.
- 2:

PLACE DRILL CHART HERE:

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
-	8.0	+3.0/-8.0	PLATED	26
-	10.0	+3.0/-10.0	PLATED	123
*	28.0	+3.0/-3.0	PLATED	5
*	37.0	+3.0/-3.0	PLATED	4
o	38.0	+3.0/-3.0	PLATED	14
B	91.0	+3.0/-3.0	PLATED	2
-	23.62	+1.18/-1.18	NON-PLATED	1
*	33.46	+1.97/-1.97	NON-PLATED	2
T	67.0	+2.0/-2.0	NON-PLATED	4
G	125.0	+2.0/-2.0	NON-PLATED	4
*	27.56x23.62	+1.97/-1.97	PLATED	2
*	27.56x27.56	+1.97/-1.97	PLATED	2
=	74.8x23.62	+1.97/-1.97	PLATED	2
=	78.74x27.56	+1.97/-1.97	PLATED	2
*	33.46x19.69	+1.18/-1.18	NON-PLATED	1

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 NUMBER OF LAYERS: 6
 MIN. TRACK WIDTH: 8.0 MIL
 MIN. CLEARANCE : X.X MIL
 MIN. VIA PAD/DRILL: 08/16 MIL

MIN. ANNULAR RING 2 MIL EXTERNAL PER IPC-6012C CLASS 2
 REGISTRATION TOLERANCES: METAL +/- X MIL, HOLES +/- X MIL
 IMPEDANCE CONTROL: NONE YES - SEE TABLE 1
 MIXED DIELECTRIC: NO YES
 LAMINATE MATERIAL:
 FR-4 HIGH Tg ROGERS 4350B OTHER: _____
 THICKNESS:
 0.062" +/-10% 0.093" +/-10% OTHER: _____
 TOLERANCE: IPC-6012C TYPE 3 CLASS 2 OTHER +/-
 BOW & TWIST: IPC-6012C TYPE 3 CLASS 2 OTHER +/-
 COPPER THICKNESS (FINISHED):
 OUTER: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.
 INNER SIGNAL: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.
 INNER PLANE: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.
 OTHER: _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDERMASK: (PER IPC-6011,6012)
 TOP BOTTOM
 SOLDERMASK COLOR: GREEN BLUE OTHER _____
 THROUGH-HOLE VIA TREATMENT:
 OPEN TENTED IDENTIFIER: ALL _____
 VIA-FILL USING NON-CONDUCTIVE EPOXY:
 NO YES IDENTIFIER: ALL X MIL VIAS

THIEVING ALLOWED: YES NO
 BOARD SURFACE TREATMENT:
 NICKEL/GOLD (ENIG) ORGANIC (OSP) HASL ENERPIG
 IMMERSION TIN OTHER _____
 FOR WIRE BONDING:
 HARD GOLD SOFT GOLD PER SUPPLIED ARTWORK
 ADDITIONAL REQUIREMENTS:
 MICRO-SECTION TDR REPORTS/COUPONS ELECTRICAL TEST
 CERTIFICATES OF COMPLIANCE RoHS UL 94V-0
 VENDOR MARKING:
 VENDOR DATE CODE,UL,LOGO: ETCH SILKSCREEN BREAK-AWAY
 IN AN OPEN AREA WHERE INDICATED (SEE DRAWING)

D

C

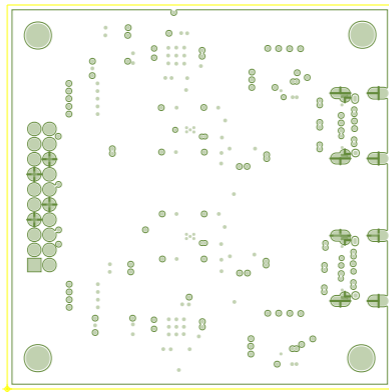
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CAD ORIGIN

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